



(3583)

2022/03/16

Safe Harbor Statement



- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

Scientech Corp (3583: TT)

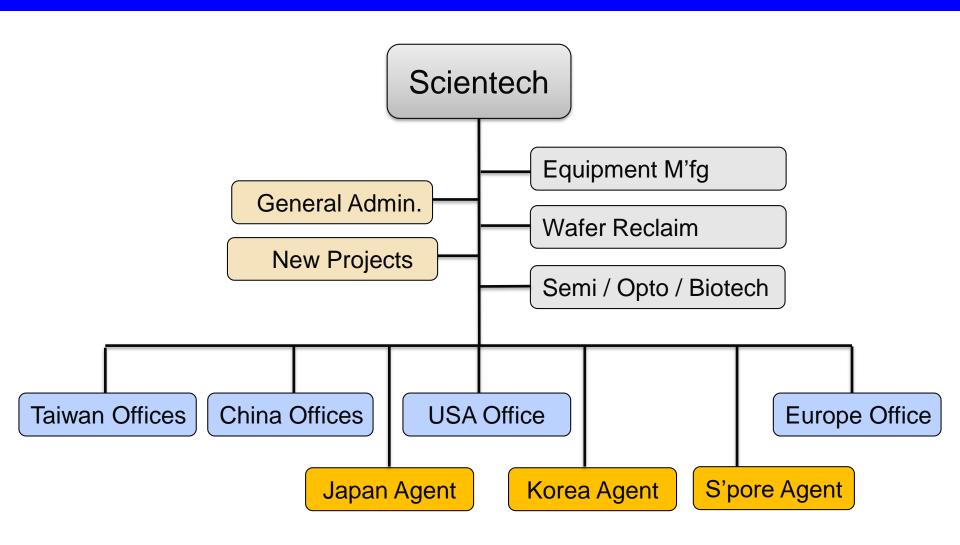


Company 1979/10/17 Establishment **IPO** 2013/3/12 Capital NT\$ 811 Million Chairman H.L. Hsieh **CEO** M.T. Hsu Equipment Manufacturing . Wafer Reclaim . Products

Trading(Agent/Distributor)

Organization







Business

Overview

Products

Corporate Governance

> Future Prospect

Business Overview

Income Statement



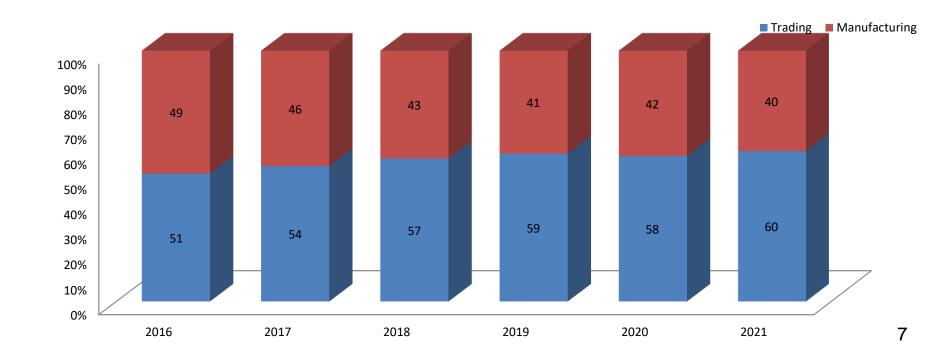
Units: NT \$ M	2016	2017	2018	2019	2020	2021
Revenues	3,495	3,539	3,988	3,949	3,580	4,684
Gross Profit	1,178	1,251	1,448	1,384	1,456	1,667
Operating Expenses	835	829	935	997	991	1,112
Operating Income	343	423	514	387	465	555
Other Income and Expenses	21	(8)	26	16	(76)	(31)
Income Before Tax	363	415	540	403	389	524
Net Income	292	328	418	323	305	420
EPS	3.60	4.05	5.16	4.02	3.80	5.23
Gross Margin	34%	35%	36%	35%	41%	36%
Operating Margin	10%	12%	13%	10%	13%	12%
ncome Before Tax margin	10%	12%	14%	10%	11%	11%

Business Overview

Products Mix



Units: %	2016	2017	2018	2019	2020	2021	Gross Margin
Trading	51	54	57	59	58	60	Below Average
Manufacturing	49	46	43	41	42	40	Above Average

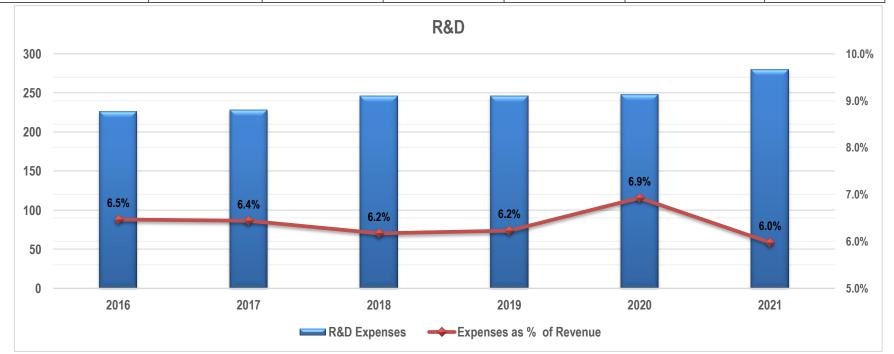


Business Overview

R&D Expenses



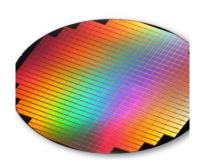
Units: NT \$ M	2016	2017	2018	2019	2020	2021
R&D Expenses	226	228	246	246	248	280
Expenses as % of Revenue	6.5%	6.4%	6.2%	6.2%	6.9%	6.0%

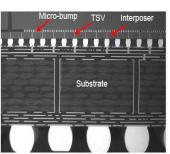


What We Do



- Industries which we serve:
 - Semiconductor (Front-End and Advanced Packaging)
 - Compound Semiconductor
 - LED / Mini LED / Micro LED
 - Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)
 - Solar Cell / Battery
 - Biotech / Chemistry Analysis / Scientific Instrument,...











Product and Technology



- Semiconductor
- Compound SEMI
- LED / Micro LED
- Flat Panel Display
- Solar Cell / Battery
- Biotech
- Scientific Inst.



- Wet-Process Tools
- Wafer Temporary Bonding **Debonding System**
- SEMI / Compound / LED

Representative / Distributor

Wafer Reclaim Service

- 12" Si Wafer
- 6" SiC Wafer

Wafer Reclaim Service



Scientech Corp.



- 12" Wafer Reclaim
 - Capacity: 120K→140K
 →160K/ Month
 - Cu and Non-Cu Process

SiC Post Slicing Process and Reclaim

• Capacity: 800 / Month



Wet Process Equipment

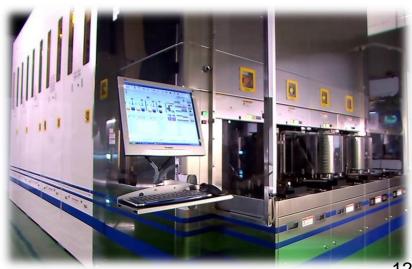


Scientech Corp.



- Wet-Bench / Single-Wafer Wet Process Equipment
- Applications:
 - Advanced Packaging Process
 - Semiconductor Front-End Process
 - Compound Semiconductor
 - Microelectromechanical Systems (MEMS)
 - High-End LED Fully-Automatic Advanced Process





Temporary Bonding Debonding System



Scientech Corp.



- Temporary Bonding Debonding System (TBDB)
- Application: IGBT Power Device, Advanced Packaging for Semiconductor and LED
 - Temporary Bonding System
 - Temporary Debonding System
 - Release Layer Formation System
 - Carrier (Glass) Recycling System





Trading (Agent/Distributor)



























Exclusive Agency

















Hirata















Supply Chain

Partnership



Corporate Governance

Initial Certification

2014/5/27

ISO Certifications



2019/11/20

Issue 3. Certified since 2019/4/30

Valid Date:

2019/4/30 ~ 2022/4/30



Issue 1. Certified since

Valid Date:

2019/11/20 ~ 2022/11/19



Issue 1. Certified since 2021/09/29

Valid Date:

2021/09/29 ~ 2024/09/28



Valid Date: SGS 2020/5/28 ~ 2023/5/27 Scientech Corporation TUV NORD ISO 14001:2015 CERTIFICATE JAF Management system as per ISO 9001: 2015 9

ISO45001

ISO27001

Information **Security**



ISO22301

BCM

ISO14001

Issue 4. Certified since

2019/4/30 ~ 2022/4/30

2010/3/24

Valid Date:



Corporate Governance

Intellectual Property Management (TIPS – AA) s





Future Prospect

The Growing Market



- Demand continues to grow: 5G, efficient computing, AI, IoT, AR, automotive electronics, cloud > etc.
- The continuous development of 12" semiconductor advanced process
 - Front-End: 5nm \ 3nm \ 2nm \ 1nm
 - Advanced Packaging: Fan-Out \ WLCSP \ Flip-Chip \ 2.5D \ 3D \ etc.
- The continuous expansion of China semiconductor fabs in recent years
- The demand of 8" semiconductor fab is higher than the supplying capacity
- Compound semiconductor :
 - The investments of electrical car and 5G are growing tremendously
 - The third generation of semiconductor arises. The demand of high power and high frequency semiconductor are growing rapidly.
- The new application of Mini LED & Micro LED starts and it will lead the LED industry grows again.

Q & A





Thank You!